

<sup>\*</sup> Any targeted thickness .0046" and greater shall have a minimum tolerance of +/-.001 after lamination.

PRELIMINARY STACK UP

<sup>\*</sup> Any targeted thickness .0045" and below shall not be held to the minimum dielectric .0035429" as specified in IPC-6012 section 3.6.2.17. Unless agreed upon in writing from Summit Interconnect. The minimum thickness per this exception shall not be less than .0009839" per IPC-6012 section 3.6.2.17.

<sup>\*</sup> Summit Interconnect is not responsible for any build that does not meet IPC-6012 Bow & Twist requirements due to unbalanced dielectrics, unbalanced copper percentages or copper weights.

	Thk[A] (Mil)Thk[B] (Mil)Thk[D] (MilFamily[D]				VendoThk[C] (Mil)	
	1.5486 0.61 2 0.6	1.5486 0.61 2 0.6				
1.4205]	0.844	0.844 1.4205	1.4205	LF-Pyralux	Dupont	1.4205
	0.61 2 0.61	0.61 2 0.61	0.61 2 0.61	RF775-RA	Matrix	0.61 2 0.61
292]	1.8292	1.8292	1.8292	FR-Pyralux	Dupont	1.8292
=[2]	2		2	ЗМ	3M	
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